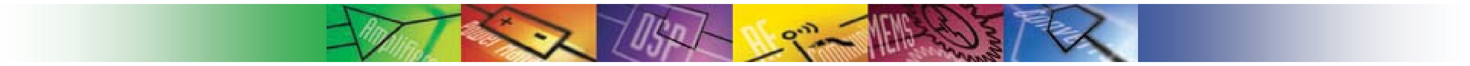

Product / Package Information

Package	LFCSP
Body Size (mm)	5 X 5 X 0.90 (3.7 X 1.6 EP & 3.34 X 1.62 EP)
Lead Count	32
Terminal Finish	100 Sn
MS Number	MS011335D

Environmental Information

RoHS Compliant	Yes with exemption
High Temperature Compliant	Yes
Halogen Free Compliant	Yes
REACH SVHC Compliant	Yes

Materials Declaration

Molding Compound

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Silica	60676-86-0	4.37E-02	93.7	937000	57.45	574529
Thermosets	Epoxy Resin	Proprietary	1.40E-03	3.0	30000	1.84	18395
Thermosets	Phenol Resin	Proprietary	1.40E-03	3.0	30000	1.84	18395
Other inorganic materials	Carbon Black	1333-86-4	1.40E-04	0.3	3000	0.18	1839
Subtotal			4.66 E-02	100.00	1000000	61.32	613158

Leadframe

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Copper & its alloys	Copper	7440-50-8	1.37 E-02	97.50	975000	18.03	180349
Copper & its alloys	Iron	7439-89-6	3.30 E-04	2.35	23500	0.43	4347
Copper & its alloys	Zinc	7440-66-6	1.69 E-05	0.12	1200	0.02	222
Copper & its alloys	Phosphorus	7723-14-0	4.22 E-06	0.03	300	0.01	55
Subtotal			1.41 E-02	100.00	1000000	18.50	184974

Copper Clip

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Copper & its alloys	Copper	7440-50-8	4.78 E-03	97.50	339842	6.29	62862
Copper & its alloys	Iron	7439-89-6	1.15 E-04	2.35	8191	0.15	1515
Copper & its alloys	Zinc	7440-66-6	5.88 E-06	0.12	418	0.01	77
Copper & its alloys	Phosphorus	7723-14-0	1.47 E-06	0.03	105	0.00	19
Subtotal			4.90 E-03	100.00	348556	6.45	64474

Internal Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Silver	7440-22-4	1.42 E-04	100.0	1000000	0.19	1868

External Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Tin & its alloys	Tin	7440-31-5	1.90 E-03	100.0	1000000	2.50	25000

Bond Wires

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Gold	7440-57-5	8.00 E-04	100.0	1000000	1.05	10526

Chip

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Doped Silicon	7440-21-3	4.30 E-03	100.0	1000000	5.66	56579

Die Attach

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Silver	7440-22-4	3.60 E-04	90.00	900000	0.47	4737
Other organic materials	Acrylic resin	TS#10230	2.00 E-05	5.00	50000	0.03	263
Other organic materials	Acrylate monomer	TS#10050	2.00 E-05	5.00	50000	0.03	263
Subtotal			4.00 E-04	100.00	1000000	0.53	5263

Solder Paste

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Lead and its Alloys	Lead	7439-92-1	2.68 E-03	92.50	925000	3.53	35296
Lead and its Alloys	Tin	7440-31-5	1.45 E-04	5.00	50000	0.19	1908
Lead and its Alloys	Silver	7440-22-4	7.25 E-05	2.50	25000	0.10	954
			2.90 E-03	100.00	1000000	3.82	38158

	Weight (g)	Percentage (%)	PPM
Package Totals	**7.60 E-02**	100.00	1000000

Note: The information provided in this declaration are true to the best of ADI's knowledge.
ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability to any inaccuracy of such information.

ANALOG DEVICES
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